

DERWENT-ACC-NO: 1989-289352

DERWENT-WEEK: 198940

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TITLE: Removing silicone resin film on substrate - by exposing  
film to oxygen plasma while applying heat, and dissolving  
film with water soln. of hydrofluoric acid NoAbstract Dwg  
1/2

PATENT-ASSIGNEE: FUJITSU LTD[FUIT]

PRIORITY-DATA: 1988JP-0038009 (February 19, 1988)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 01212441 A	August 25, 1989	N/A	008	N/A

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
JP 01212441A	N/A	1988JP-0038009	February 19, 1988

INT-CL (IPC): H01L021/30

ABSTRACTED-PUB-NO:

EQUIVALENT-ABSTRACTS:

TITLE-TERMS: REMOVE SILICONE RESIN FILM SUBSTRATE EXPOSE FILM OXYGEN  
PLASMA

APPLY HEAT DISSOLVE FILM WATER SOLUTION HYDROFLUORIC ACID  
NOABSTRACT

DERWENT-CLASS: A26 A35 L03 U11

CPI-CODES: A06-A00D; A11-C04D; A11-C04E; A12-B01C; A12-E01; L04-C09; L04-C12E;

EPI-CODES: U11-C07A1; U11-C07B; U11-C07D3;